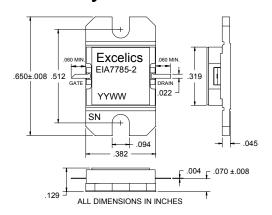


UPDATED 11/16/2006

7.70-8.50GHz 2-Watt Internally Matched Power FET

FEATURES

- 7.70-8.50GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +34 dBm Output Power at 1dB Compression
- 12.5 dB Power Gain at 1dB Compression
- 33% Power Added Efficiency
- Hermetic Metal Flange Package
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS ($T_a = 25$ °C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹		TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 7.70-8.50GHz$ $V_{DS} = 8V$, $I_{DSQ} \approx 800mA$	33.0	34.0		dBm
G _{1dB}	Gain at 1dB Compression $f = 7.70-8.50GHz$ $V_{DS} = 8V$, $I_{DSQ} \approx 800mA$	11.5	12.5		dB
ΔG	Gain Flatness $f = 7.70-8.50GHz$ $V_{DS} = 8V, I_{DSQ} \approx 800mA$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 8V$, $I_{DSQ} \approx 800$ mA $f = 7.70-8.50$ GHz		33		%
Id _{1dB}	Drain Current at 1dB Compression f = 7.70-8.50GHz		900	1100	mA
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		1400	1800	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 14 \text{ mA}$		-1.0	-2.5	V
R _{TH}	Thermal Resistance ²		10	11	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

ABSOLUTE MAXIMUM RATING^{1,2}

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
V _{DS}	Drain-Source Voltage	12	8V
V_{GS}	Gate-Source Voltage	-5	-3V
lgsf	Forward Gate Current	21.6mA	7.2mA
lgsr	Reverse Gate Current	-3.6mA	-1.2mA
Pin	Input Power	33dBm	@ 3dB Compression
Tch	Channel Temperature	175 °C	175°C
Tstg	Storage Temperature	-65 to +175 °C	-65 to +175 °C
DataSheet4U.com	Total Power Dissipation	13W	13W

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

Specifications are subject to change without notice.

^{2.} Overall Rth depends on case mounting.



EIA7785-2

UPDATED 11/16/2006

7.70-8.50GHz 2-Watt Internally Matched Power FET

DISCLAIMER

EXCELICS SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. EXCELICS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN.

LIFE SUPPORT POLICY

EXCELICS SEMICONDUCTOR PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF EXCELICS SEMICONDUCTOR, INC. AS HERE IN:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness

www.DataSheet4U.com